

# FDD2582

## MOSFET, N-Channel, POWERTRENCH®

150 V, 21 A, 66 mΩ

### Features

- $r_{DS(ON)} = 58 \text{ m}\Omega$  (Typ.),  $V_{GS} = 10 \text{ V}$ ,  $I_D = 7 \text{ A}$
- $Q_g(\text{tot}) = 19 \text{ nC}$  (Typ.),  $V_{GS} = 10 \text{ V}$
- Low Miller Charge
- Low QRR Body Diode
- UIS Capability (Single Pulse and Repetitive Pulse)
- These Devices are Pb-Free, Halide Free and are RoHS Compliant

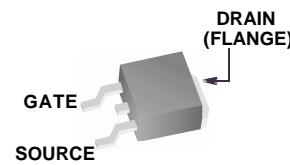
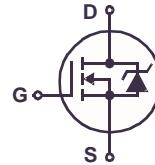
### Applications

- DC/DC Converters and Off-Line UPS
- Distributed Power Architectures and VRMs
- Primary Switch for 24 V and 48 V Systems
- High Voltage Synchronous Rectifier
- Direct Injection / Diesel Injection Systems
- 42 V Automotive Load Control
- Electronic Valve Train System



ON Semiconductor®

[www.onsemi.com](http://www.onsemi.com)



DPAk3 (TO-252 3 LD)  
CASE 369AS

### MARKING DIAGRAM



\$Y	= ON Semiconductor Logo
&Z	= Assembly Plant Code
&3	= Numeric Date Code
&K	= Lot Code
FDD2582	= Specific Device Code

### ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

# FDD2582

## MOSFET MAXIMUM RATINGS ( $T_C = 25^\circ\text{C}$ , Unless otherwise noted)

Symbol	Parameter	Ratings	Units
$V_{DSS}$	Drain to Source Voltage	150	V
$V_{GS}$	Gate to Source Voltage	$\pm 20$	V
$I_D$	Drain Current –Continuous ( $T_C = 25^\circ\text{C}$ , $V_{GS} = 10$ V)	21	A
	–Continuous ( $T_C = 100^\circ\text{C}$ , $V_{GS} = 10$ V)	15	
	–Continuous ( $T_{amb} = 25^\circ\text{C}$ , $V_{GS} = 10$ V, $R_{\theta JA} = 52^\circ\text{C/W}$ )	3.7	
	–Pulsed	See Figure 4	
$E_{AS}$	Single Pulse Avalanche Energy (Note 1)	59	mJ
$P_D$	Power Dissipation	95	W
	Derate above $25^\circ\text{C}$	0.63	$^\circ\text{C}/\text{W}$
$T_J$ , $T_{STG}$	Operating and Storage Temperature	–55 to 175	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Starting  $T_J = 25^\circ\text{C}$ ,  $L = 1.17$  mH,  $I_{AS} = 10$  A.

## THERMAL CHARACTERISTICS

Symbol	Parameter	Ratings	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case TO-252	1.58	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient TO-252	100	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient TO-252, 1 in <sup>2</sup> copper pad area	52	

## PACKAGE MARKING AND ORDERING INFORMATION

Device Marking	Device	Package	Shipping <sup>†</sup>
FDD2582	FDD2582	DPAK3 (TO-252 3 LD) (Pb-Free, Halide Free)	2500 units / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D

# FDD2582

ELECTRICAL CHARACTERISTICS ( $T_C = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>OFF CHARACTERISTICS</b>						
$\text{BV}_{\text{DSS}}$	Drain to Source Breakdown Voltage	$I_D = 250 \mu\text{A}, V_{GS} = 0 \text{ V}$	150			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS} = 120 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 120 \text{ V}, V_{GS} = 0 \text{ V}, T_C = 150^\circ\text{C}$			1 250	$\mu\text{A}$
$I_{\text{GSS}}$	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}$			$\pm 100$	nA

## ON CHARACTERISTICS

$V_{GS(\text{TH})}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu\text{A}$	2		4	V
$r_{DS(\text{on})}$	Drain to Source On Resistance	$I_D = 7 \text{ A}, V_{GS} = 10 \text{ V}$ $I_D = 4 \text{ A}, V_{GS} = 6 \text{ V}$ $I_D = 7 \text{ A}, V_{GS} = 10 \text{ V}, T_C = 150^\circ\text{C}$		0.058 0.066 0.151	0.066 0.099 0.172	$\Omega$

## DYNAMIC CHARACTERISTICS

$C_{\text{ISS}}$	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	1295		pF
$C_{\text{OSS}}$	Output Capacitance		145		pF
$C_{\text{RSS}}$	Reverse Transfer Capacitance		30		pF
$Q_{g(\text{TOT})}$	Total Gate Charge at 10 V	$V_{GS} = 0 \text{ V to } 10 \text{ V}$ $V_{DD} = 75 \text{ V}, I_D = 7 \text{ A}, I_g = 1.0 \text{ mA}$	19	25	nC
$Q_{g(\text{TH})}$	Threshold Gate Charge		2.4	3.2	nC
$Q_{gs}$	Gate to Source Gate Charge		6.2		nC
$Q_{gs2}$	Gate Charge Threshold to Plateau		3.8		nC
$Q_{gd}$	Gate to Drain "Miller" Charge		4.2		nC

## RESISTIVE SWITCHING CHARACTERISTICS ( $V_{GS} = 10 \text{ V}$ )

$t_{\text{ON}}$	Turn-On Time	$V_{DD} = 75 \text{ V}, I_D = 7 \text{ A}$ $V_{GS} = 10 \text{ V}, R_{GS} = 16 \Omega$		41	ns
$t_{d(\text{ON})}$	Turn-On Delay Time		8		ns
$t_r$	Rise Time		19		ns
$t_{d(\text{OFF})}$	Turn-Off Delay Time		32		ns
$t_f$	Fall Time		19		ns
$t_{\text{OFF}}$	Turn-Off Time			77	ns

## DRAIN-SOURCE DIODE CHARACTERISTICS

$V_{SD}$	Source to Drain Diode Voltage	$I_{SD} = 7 \text{ A}$ $I_{SD} = 4 \text{ A}$		1.25 1.0	V
$t_{rr}$	Reverse Recovery Time	$I_{SD} = 7 \text{ A}, \Delta I_{SD}/\Delta t = 100 \text{ A}/\mu\text{s}$		67	ns
$Q_{RR}$	Reverse Recovery Charge	$I_{SD} = 7 \text{ A}, \Delta I_{SD}/\Delta t = 100 \text{ A}/\mu\text{s}$		134	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

**TYPICAL CHARACTERISTICS**  $T_C = 25^\circ\text{C}$  unless otherwise noted.

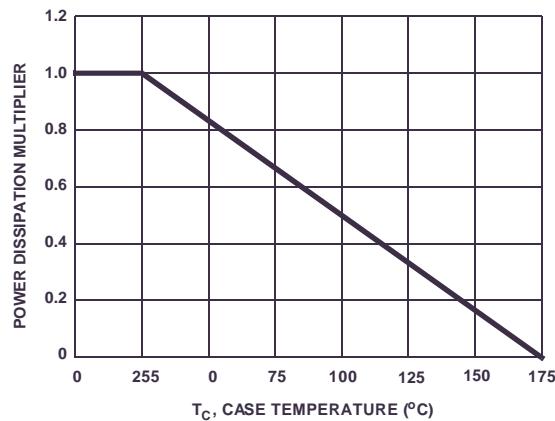


Figure 1. Normalized Power Dissipation vs. Ambient Temperature

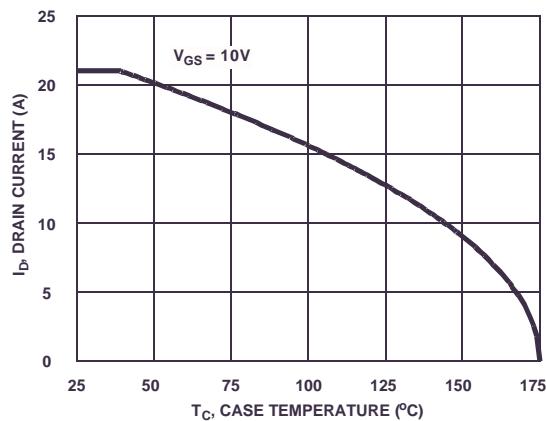


Figure 2. Maximum Continuous Drain Current vs. Case Temperature

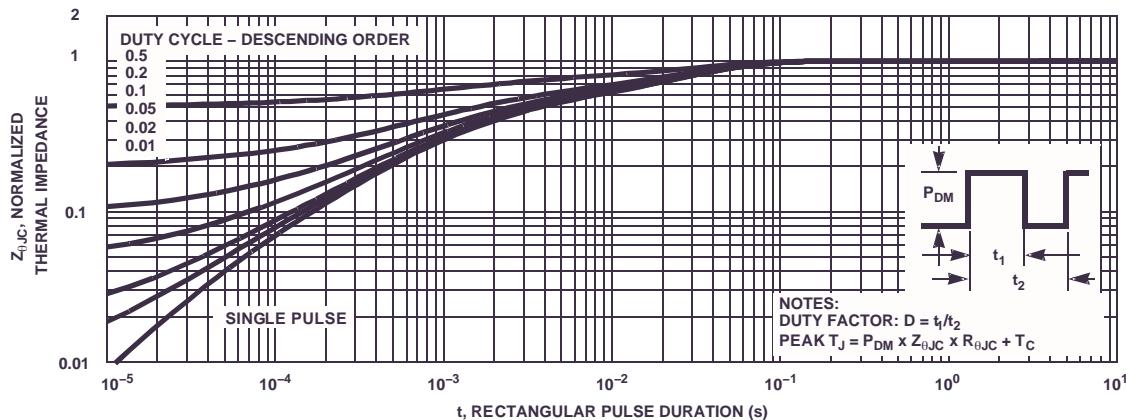


Figure 3. Normalized Maximum Transient Thermal Impedance

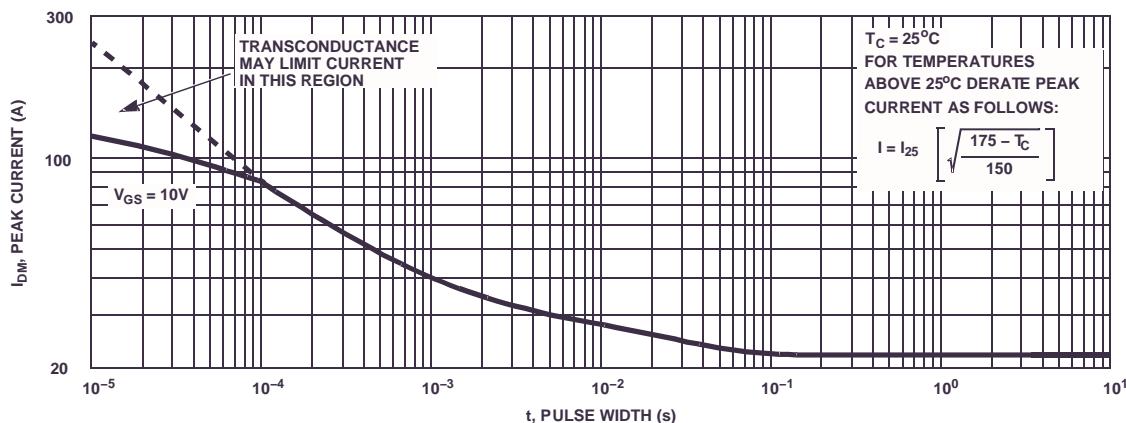


Figure 4. Peak Current Capability

## TYPICAL CHARACTERISTICS $T_C = 25^\circ\text{C}$ unless otherwise noted.

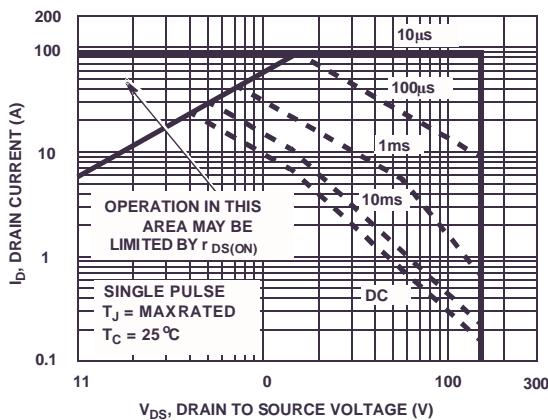
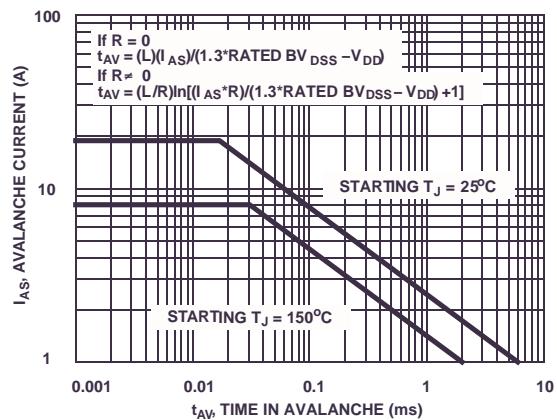


Figure 5. Forward Bias Safe Operating Area



Note: Refer to Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching Capability

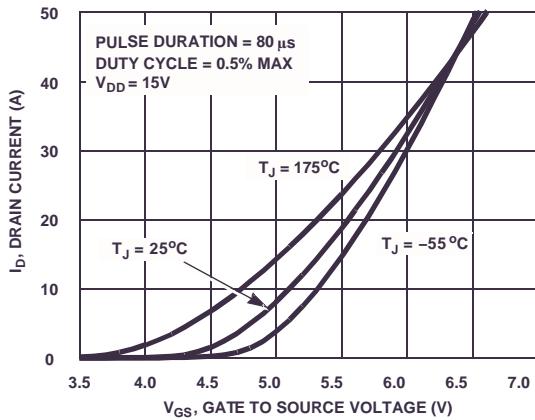


Figure 7. Transfer Characteristics

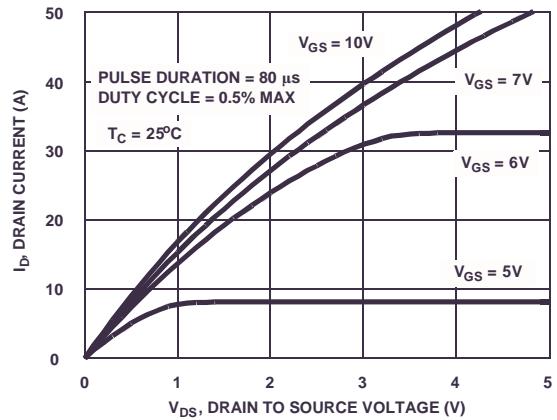


Figure 8. Saturation Characteristics

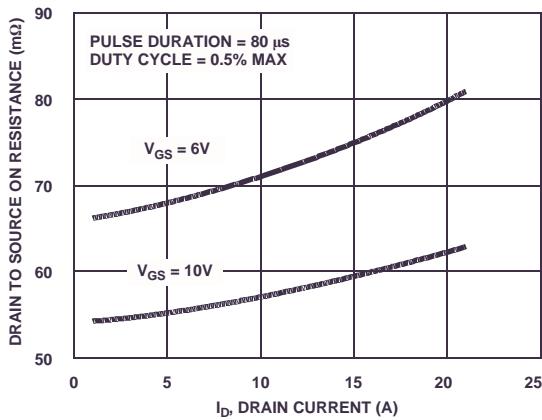


Figure 9. Drain to Source On Resistance vs. Drain Current

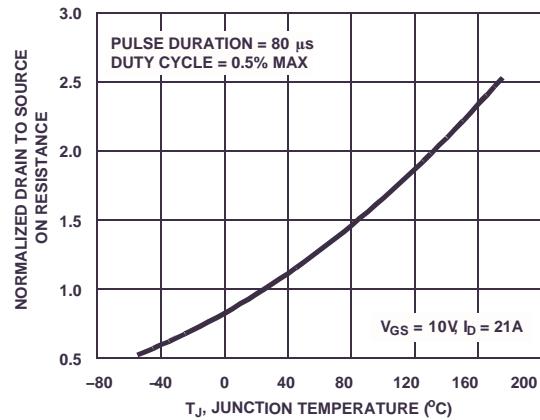
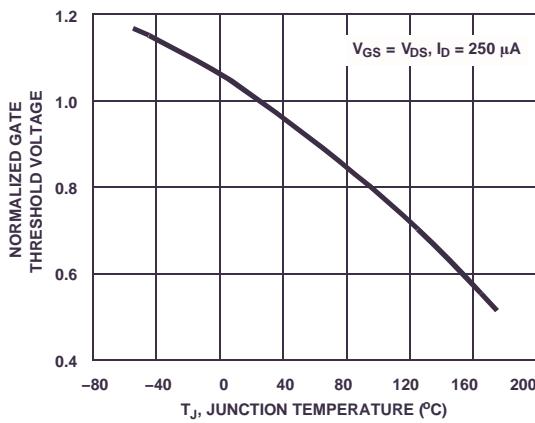
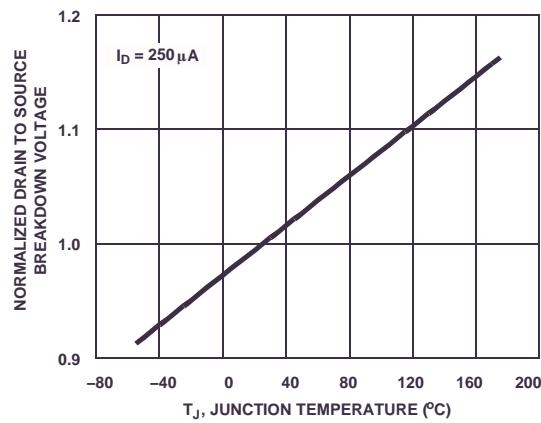


Figure 10. Normalized Drain to Source On Resistance vs. Junction Temperature

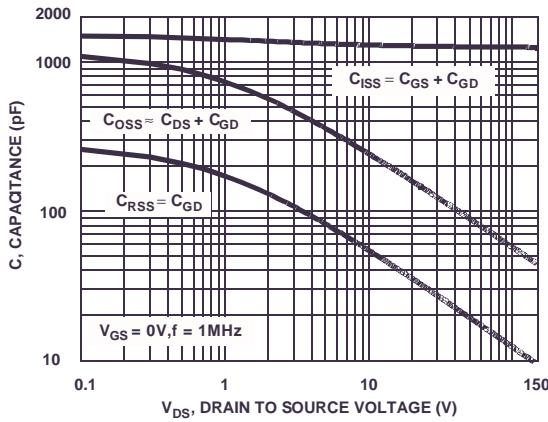
**TYPICAL CHARACTERISTICS**  $T_C = 25^\circ\text{C}$  unless otherwise noted.



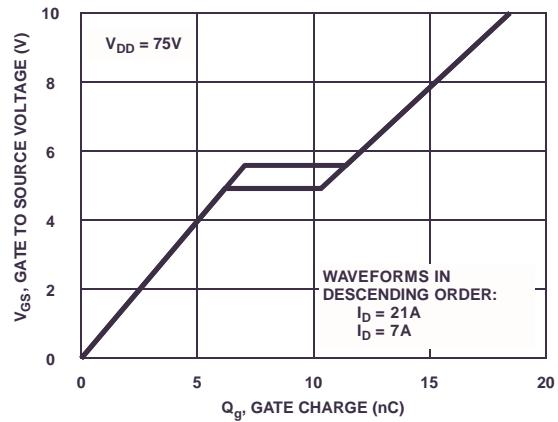
**Figure 11. Normalized Gate Threshold vs. Junction Temperature**



**Figure 12. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature**



**Figure 13. Capacitance vs. Drain to Source Voltage**



**Figure 14. Gate Charge Waveforms for Constant Gate Currents**

## TEST CIRCUITS AND WAVEFORMS

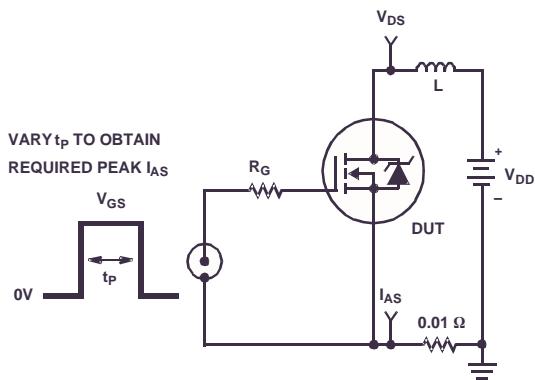


Figure 15. Unclamped Energy Test Circuit

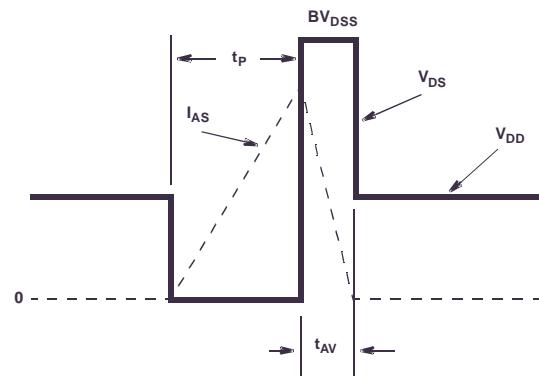


Figure 16. Unclamped Energy Waveforms

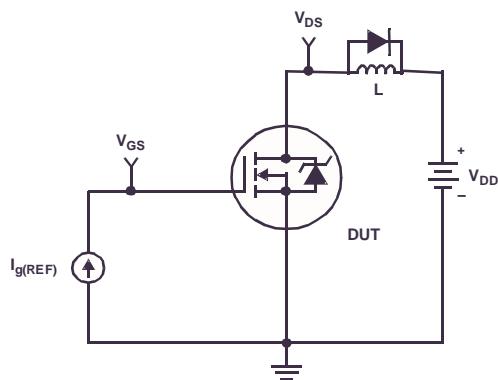


Figure 17. Gate Charge Test Circuit

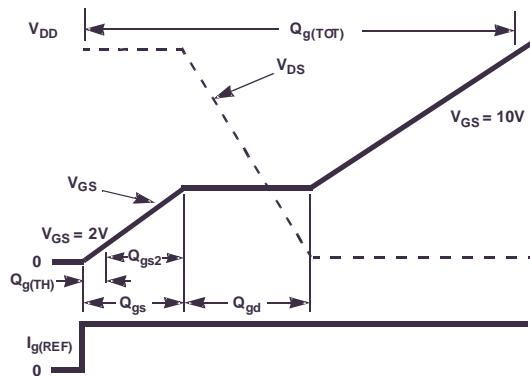


Figure 18. Gate Charge Waveforms

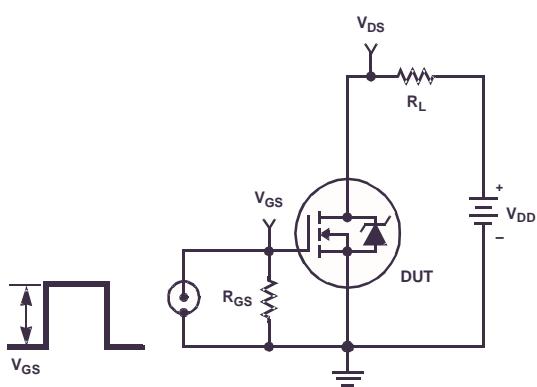


Figure 19. Switching Time Test Circuit

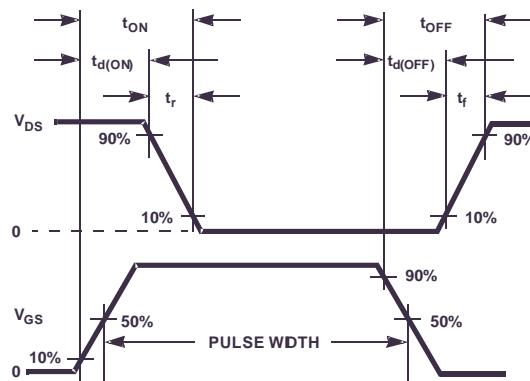


Figure 20. Switching Time Waveforms

### Thermal Resistance vs. Mounting Pad Area

The maximum rated junction temperature,  $T_{JM}$ , and the thermal resistance of the heat dissipating path determines the maximum allowable device power dissipation,  $P_{DM}$ , in an application. Therefore, the application's ambient temperature,  $T_A$  ( $^{\circ}$ C), and thermal resistance  $R_{\theta JA}$  ( $^{\circ}$ C/W) must be reviewed to ensure that  $T_{JM}$  is never exceeded. Equation 1 mathematically represents the relationship and serves as the basis for establishing the rating of the part.

$$P_{DM} = \frac{(T_{JM} - T_A)}{R_{\theta JA}} \quad (\text{eq. 1})$$

In using surface mount devices such as the TO-252 package, the environment in which it is applied will have a significant influence on the part's current and maximum power dissipation ratings. Precise determination of  $P_{DM}$  is complex and influenced by many factors:

1. Mounting pad area onto which the device is attached and whether there is copper on one side or both sides of the board.
2. The number of copper layers and the thickness of the board.
3. The use of external heat sinks.
4. The use of thermal vias.
5. Air flow and board orientation.
6. For non steady state applications, the pulse width, the duty cycle and the transient thermal response of the part, the board and the environment they are in.

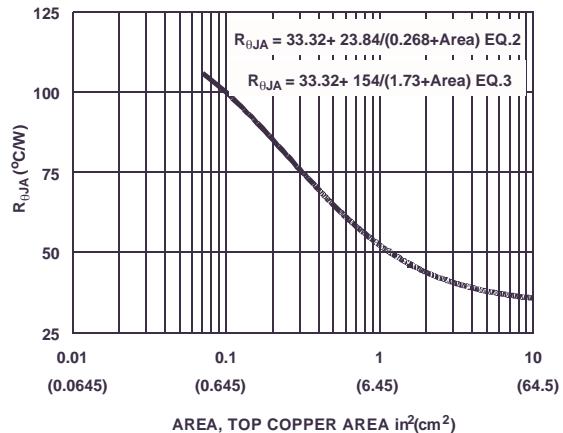
ON Semiconductor provides thermal information to assist the designer's preliminary application evaluation. Figure 21 defines the  $R_{\theta JA}$  for the device as a function of the top copper (component side) area. This is for a horizontally positioned FR-4 board with 1oz copper after 1000 seconds of steady state power with no air flow. This graph provides the necessary information for calculation of the steady state

junction temperature or power dissipation. Pulse applications can be evaluated using the ON Semiconductor device Spice thermal model or manually utilizing the normalized maximum transient thermal impedance curve.

Thermal resistances corresponding to other copper areas can be obtained from Figure 21 or by calculation using Equation 2 or 3. Equation 2 is used for copper area defined in inches square and equation 3 is for area in centimeters square. The area, in square inches or square centimeters is the top copper area including the gate and source pads.

$$R_{\theta JA} = 33.32 + \frac{23.84}{(0.268 + \text{Area})} \quad \text{Area in [in}^2\text{]} \quad (\text{eq. 2})$$

$$R_{\theta JA} = 33.32 + \frac{154}{(1.73 + \text{Area})} \quad \text{Area in [cm}^2\text{]} \quad (\text{eq. 3})$$



**Figure 21. Thermal Resistance vs. Mounting Pad Area**

# FDD2582

## PSPICE Electrical Model

.SUBCKT FDD2582 2 1 3 ; rev July 2002

Ca 12 8 4e-10

Cb 15 14 4.6e-10

Cin 6 8 1.24e-9

Dbody 7 5 DbodyMOD

Dbreak 5 11 DbreakMOD

Dpcap 10 5 DpcapMOD

Ebreak 11 7 17 18 160.4

Eds 14 8 5 8 1

Egs 13 8 6 8 1

Esg 6 10 6 8 1

Evhres 6 21 19 8 1

Evtres 20 6 18 22 1

It 8 17 1

Lgate 1 9 4.88e-9

Ldrain 2 5 1.0e-9

Lsource 3 7 2.24e-9

RLgate 1 9 48.8

RLdrain 2 5 10

RLsource 3 7 22.4

Mmed 16 6 8 8 MmedMOD

Mstro 16 6 8 8 MstroMOD

Mweak 16 21 8 8 MweakMOD

Rbreak 17 18 RbreakMOD 1

Rdrain 50 16 RdrainMOD 37e-3

Rgate 9 20 1.8

RSLC1 5 51 RSLC1MOD 1.0e-6

RSLC2 5 50 1.0e3

Rsource 8 7 RsourceMOD 11.9e-3

Rvhres 22 8 RvhresMOD 1

Rvtres 18 19 RvtresMOD 1

S1a 6 12 13 8 S1AMOD

S1b 13 12 13 8 S1BMOD

S2a 6 15 14 13 S2AMOD

S2b 13 15 14 13 S2BMOD

Vbat 22 19 DC 1

ESLC 51 50 VALUE={(V(5,51)/ABS(V(5,51)))\*(PWR(V(5,51)/(1e-6\*42),2.5))}

.MODEL DbodyMOD D (IS=2.3E-12 RS=5.3e-3 TRS1=2.2e-3 TRS2=4.5e-7  
+ CJO=8.8e-10 M=0.64 TT=3.8e-8 XTI=4.2)

.MODEL DbreakMOD D (RS=0.4 TRS1=1.4e-3 TRS2=-5e-5)

.MODEL DpcapMOD D (CJO=2.75e-10 IS=1.0e-30 N=10 M=0.67)

.MODEL MmedMOD NMOS (VTO=3.76 KP=2.7 IS=1e-30 N=10 TOX=1 L=1u W=1u RG=1.64)

.MODEL MstroMOD NMOS (VTO=4.25 KP=30 IS=1e-30 N=10 TOX=1 L=1u W=1u)

.MODEL MweakMOD NMOS (VTO=3.2 KP=0.068 IS=1e-30 N=10 TOX=1 L=1u W=1u RG=16.4 RS=0.1)

.MODEL RbreakMOD RES (TC1=1.1e-3 TC2=-1.1e-8)

.MODEL RdrainMOD RES (TC1=1.0e-2 TC2=2.6e-5)

.MODEL RSLC1MOD RES (TC1=2.7e-3 TC2=2.0e-6)

.MODEL RsourceMOD RES (TC1=1.0e-3 TC2=1.0e-6)

.MODEL RvhresMOD RES (TC1=-3.9e-3 TC2=-1.7e-5)

.MODEL RvtresMOD RES (TC1=-3.7e-3 TC2=1.9e-6)

.MODEL S1AMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-5.0 VOFF=-2.0)

.MODEL S1BMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-2.0 VOFF=-5.0)

.MODEL S2AMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-0.4 VOFF=0.3)

.MODEL S2BMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=0.3 VOFF=-0.4)

.ENDS

Note: For further discussion of the PSPICE model, consult **A New PSPICE Sub-Circuit for the Power MOSFET Featuring Global Temperature Options**; IEEE Power Electronics Specialist Conference Records, 1991, written by William J. Hepp and C. Frank Wheatley.

Figure 22. PSPICE Electrical Model

## SABER Electrical Model

```

REV July 2002
ttemplate FDD2582 n2,n1,n3
electrical n2,n1,n3
{
var i iscl
dp..model dbodymod = (isl=2.3e-12,rs=5.3e-3,trs1=2.2e-3,trs2=4.5e-7,cjo=8.8e-10,m=0.64,lt=3.8e-8,xti=4.2)
dp..model dbreakmod = (rs=0.4,trs1=1.4e-3,trs2=5.0e-5)
dp..model dplcapmod = (cjo=2.75e-10,isl=10.0e-30,nl=10,m=0.67)
m..model mmedmod = (type=_n,vto=3.76,kp=2.7,is=1e-30,tox=1)
m..model mstrongmod = (type=_n,vto=4.25,kp=30,is=1e-30,tox=1)
m..model mweakmod = (type=_n,vto=3.2,kp=0.068,is=1e-30,tox=1,rs=0.1)
sw_vcsp..model s1amod = (ron=1e-5,roff=0.1,von=-5.0,voff=-2.0)
sw_vcsp..model s1bmod = (ron=1e-5,roff=0.1,von=-2.0,voff=-5.0)
sw_vcsp..model s2amod = (ron=1e-5,roff=0.1,von=-0.4,voff=0.3)
sw_vcsp..model s2bmod = (ron=1e-5,roff=0.1,von=0.3,voff=-0.4)
c.ca n12 n8 = 4e-10
c.cb n15 n14 = 4.6e-10
c.cin n6 n8 = 1.24e-9

dp.dbody n7 n5 = model=dbodymod
dp.dbreak n5 n11 = model=dbreakmod
dp.dplcap n10 n5 = model=dplcapmod

spe.ebreak n11 n7 n17 n18 = 160.4
spe.eds n14 n8 n5 n8 = 1
spe.egs n13 n8 n6 n8 = 1
spe.esg n6 n10 n6 n8 = 1
spe.evthres n6 n21 n19 n8 = 1
spe.evtemp n20 n6 n18 n22 = 1

i.it n8 n17 = 1
I.igate n1 n9 = 4.88e-9
I.ldrain n2 n5 = 1.0e-9
I.lsouce n3 n7 = 2.24e-9

res.rlgate n1 n9 = 48.8
res.rldrain n2 n5 = 10
res.rlsouce n3 n7 = 22.4

m.mmed n16 n6 n8 n8 = model=mmedmod, l=1u, w=1u
m.mstrong n16 n6 n8 n8 = model=mstrongmod, l=1u, w=1u
m.mweak n16 n21 n8 n8 = model=mweakmod, l=1u, w=1u

res.rbreak n17 n18 = 1, tc1=1.1e-3,tc2=-1.1e-8
res.rdrain n50 n16 = 37e-3, tc1=1.0e-2,tc2=2.6e-5
res.rgate n9 n20 = 1.8
res.rslc1 n5 n51 = 1.0e-6, tc1=2.7e-3,tc2=2.0e-6
res.rslc2 n5 n50 = 1.0e-3
res.rsource n8 n7 = 11.9e-3, tc1=1.0e-3,tc2=1.0e-6
res.rvthres n22 n8 = 1, tc1=-3.9e-3,tc2=-1.7e-5
res.rvtemp n18 n19 = 1, tc1=-3.7e-3,tc2=1.9e-6
sw_vcsp.s1a n6 n12 n13 n8 = model=s1amod
sw_vcsp.s1b n13 n12 n13 n8 = model=s1bmod
sw_vcsp.s2a n6 n15 n14 n13 = model=s2amod
sw_vcsp.s2b n13 n15 n14 n13 = model=s2bmod

v.vbat n22 n19 = dc=1
equations {
i (n51->n50) +=iscl
iscl: v(n51,n50) = ((v(n5,n51)/(1e-9+abs(v(n5,n51))))*((abs(v(n5,n51)*1e6/42)** 2.5))
}
}


```

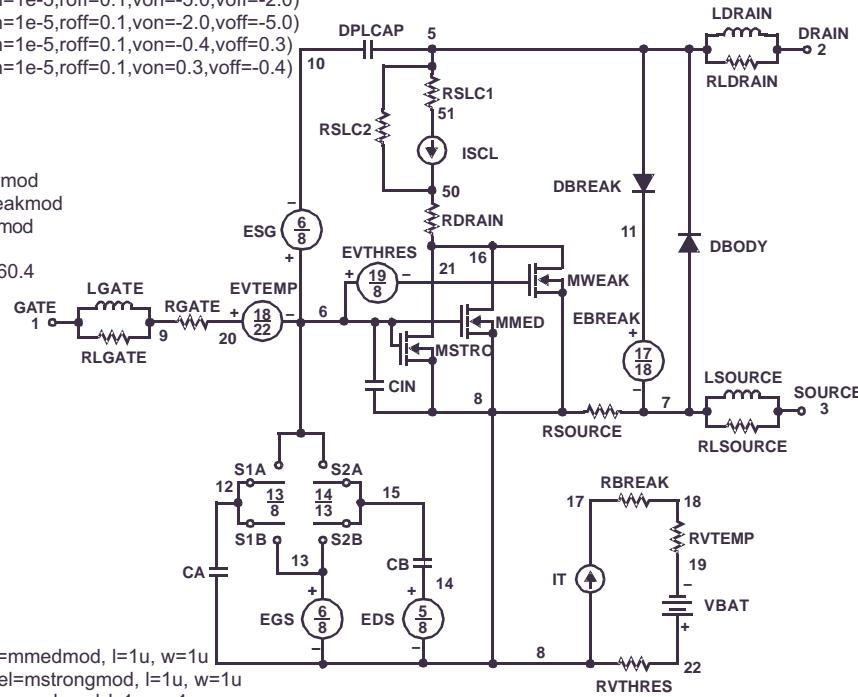


Figure 23. SABER Electrical Model

## SPICE / SABER Thermal Model

**SPICE Thermal Model**

REV 19 July 2002

FDD2582

```
CTHERM1 TH 6 1.6e-3
CTHERM2 6 5 4.5e-3
CTHERM3 5 4 5.0e-3
CTHERM4 4 3 8.0e-3
CTHERM5 3 2 8.2e-3
CTHERM6 2 TL 4.7e-2
```

```
RTERM1 TH 6 3.3e-2
RTERM2 6 5 7.9e-2
RTERM3 5 4 9.5e-2
RTERM4 4 3 1.4e-1
RTERM5 3 2 2.9e-1
RTERM6 2 TL 6.7e-1
```

**SABER Thermal Model**

SAB

```
thermal_c th, tl
{
  ctherm.ctherm1 th 6 =1.6e-3
  ctherm.ctherm2 6 5 =4.5e-3
  ctherm.ctherm3 5 4 =5.0e-3
  ctherm.ctherm4 4 3 =8.0e-3
  ctherm.ctherm5 3 2 =8.2e-3
  ctherm.ctherm6 2 tl =4.7e-2

  rrtherm.rtherm1 th 6 =3.3e-2
  rtherm.rtherm2 6 5 =7.9e-2
  rtherm.rtherm3 5 4 =9.5e-2
  rtherm.rtherm4 4 3 =1.4e-1
  rtherm.rtherm5 3 2 =2.9e-1
  rtherm.rtherm6 2 tl =6.7e-1
}
```

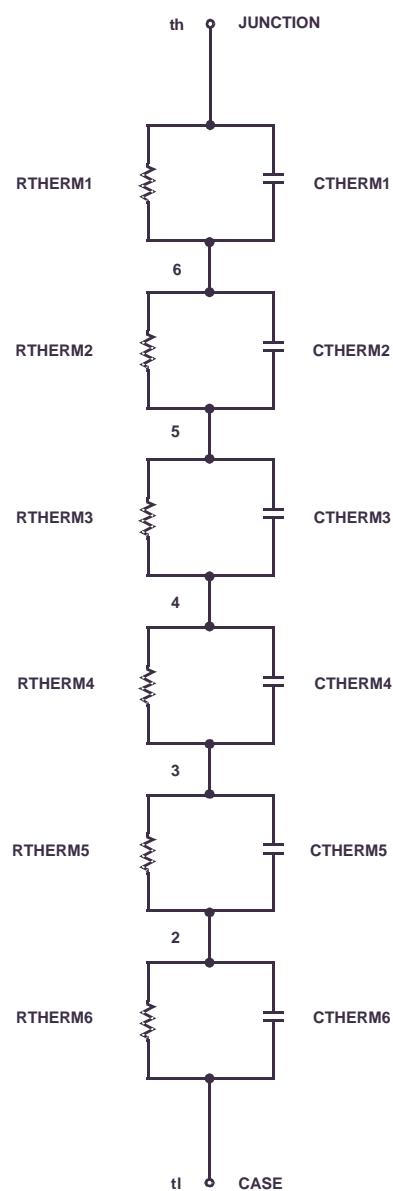
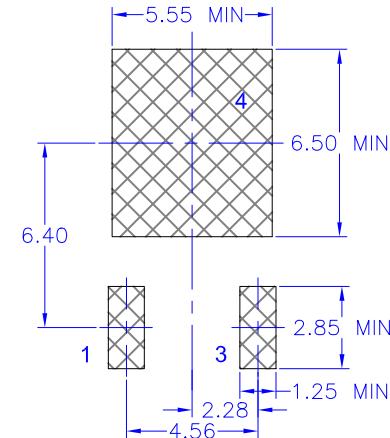
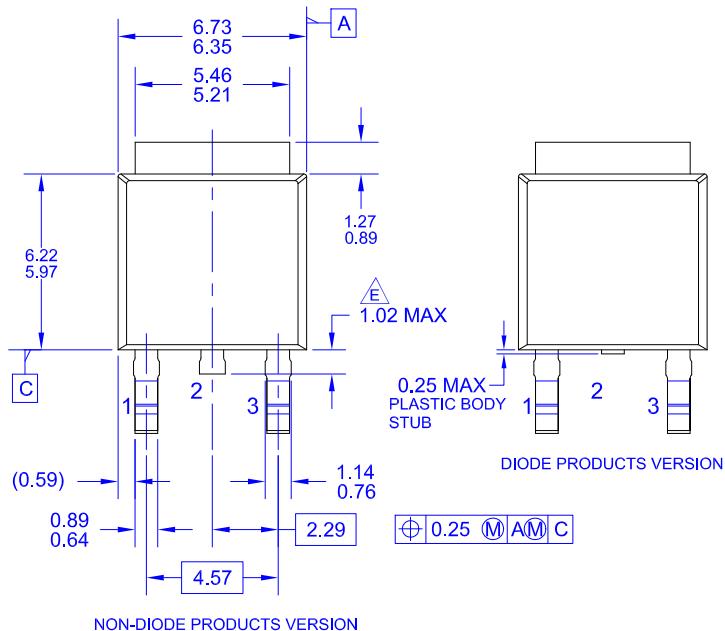


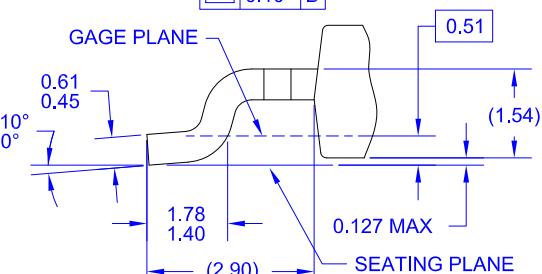
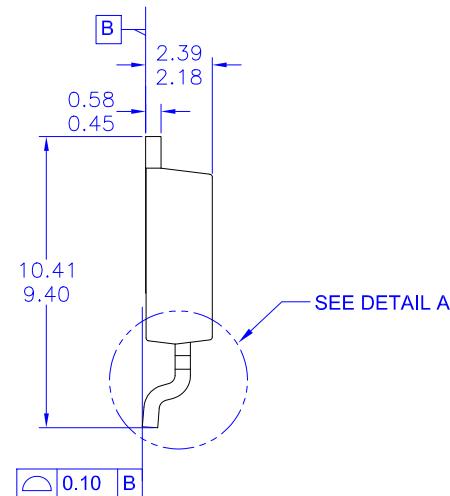
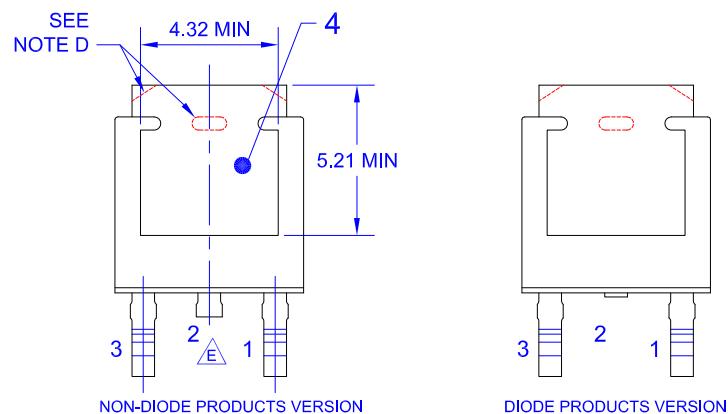
Figure 24. SPICE / SABER Thermal Model

**DPAK3 (TO-252 3 LD)**  
CASE 369AS  
ISSUE O

DATE 30 SEP 2016



LAND PATTERN RECOMMENDATION



NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC, TO-252, ISSUE C, VARIATION AA.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
- D) SUPPLIER DEPENDENT MOLD LOCKING HOLES OR CHAMFERED CORNERS OR EDGE PROTRUSION.
- E) TRIMMED CENTER LEAD IS PRESENT ONLY FOR DIODE PRODUCTS
- F) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
- G) LAND PATTERN RECOMMENDATION IS BASED ON IPC7351A STD TO228P991X239-3N.

DOCUMENT NUMBER:	98AON13810G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	DPAK3 (TO-252 3 LD)	PAGE 1 OF 1

ON Semiconductor and  are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

**onsemi, ONSEMI, and other names, marks, and brands** are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at [www.onsemi.com/site/pdf/Patent-Marking.pdf](http://www.onsemi.com/site/pdf/Patent-Marking.pdf). **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

## PUBLICATION ORDERING INFORMATION

### LITERATURE FULFILLMENT:

Email Requests to: [orderlit@onsemi.com](mailto:orderlit@onsemi.com)

**onsemi** Website: [www.onsemi.com](http://www.onsemi.com)

### TECHNICAL SUPPORT

#### North American Technical Support:

Voice Mail: 1 800-282-9855 Toll Free USA/Canada  
Phone: 011 421 33 790 2910

#### Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative